
AVR® Microcontroller Hardware Design Considerations

Introduction

This application note provides basic guidelines to be followed while designing hardware using AVR® microcontrollers. Some known problems faced in typical designs have been addressed by providing possible solutions and workarounds to resolve them.

The scope of this application note is to provide an introduction to potential design problems rather than being an exhaustive document on designing applications using AVR microcontrollers.

Note: Read application note [AVR040 - "EMC Design Considerations"](#) before starting a new design, especially if the design is expected to meet the requirements of the EMC directive or other similar directives in countries outside Europe.

Features

- Guidelines for Providing Robust Analog and Digital Power Supply
- Connection of Reset Line
- Interfacing Programmers/Debuggers to AVR Devices
- Using External Crystal or Ceramic Resonator Oscillators

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1. Abbreviations

ADC	Analog-to-Digital Converter
AREF	Analog Reference Voltage
CPU	Central Processing Unit
DC	Direct Current
DIP	Dual In-line Package
EEPROM or E²PROM	Electrically Erasable Programmable Read-Only Memory
EMC	Electromagnetic Compatibility
ESD	Electrostatic Discharge
GND	Ground
HVPP	High-Voltage/Parallel Programming
Hz	Hertz
I/O	Input and Output
IDE	Integrated Development Environment
ISP	In-System Programming
kHz	KiloHertz
LED	Light Emitting Diode
MCU	Microcontroller Unit
MHz	MegaHertz
MISO	Master In Slave Out
MOSI	Master Out Slave In
PCB	Printed Circuit Board
PDI	Program and Debug Interface
RC Filter	Resistor-Capacitor Filter
RST	Reset
SPI	Serial Peripheral Interface
TPI	Tiny Programming Interface
UPDI	Unified Program and Debug Interface
V_{CC}	Supply Voltage
XTAL	Crystal Oscillator

2. Power Supply

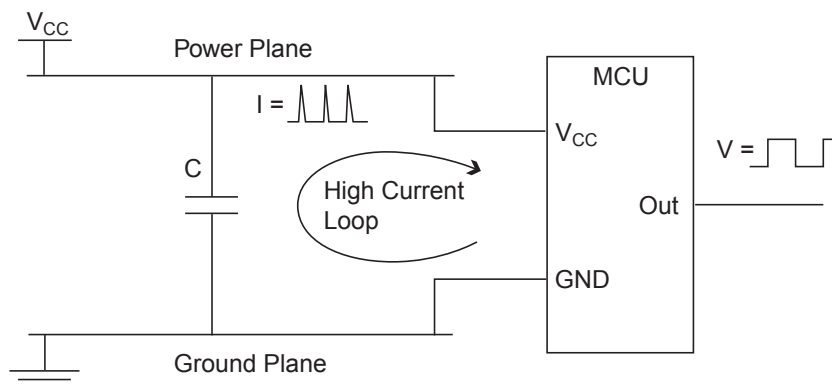
The power supply is a critical part of any hardware design and affects directly the performance of the system. Two important aspects to be considered while designing a power supply for the discrete/digital elements of an AVR device are **ESD Protection** and **Noise Emission**. These aspects are detailed in the [AVR040 application note](#), hence only a short summary is included in this document.

2.1 Digital Supply

Most AVR microcontrollers operate over a wide voltage range and draw only a few mA of supply current. This may give the impression that the power supply is not critical but, as with any digital circuit, the supply current is an average value. The current is drawn in very short spikes on the clock edges. If I/O lines are switching, the spikes will be even higher. If all eight I/O lines of an I/O port change value simultaneously, the current pulses on the power supply lines can be several hundred mA. If the I/O lines are not loaded, the pulse may last for only a few nanoseconds.

Such a current spike cannot be delivered over long power supply lines; the main source should be the decoupling capacitor.

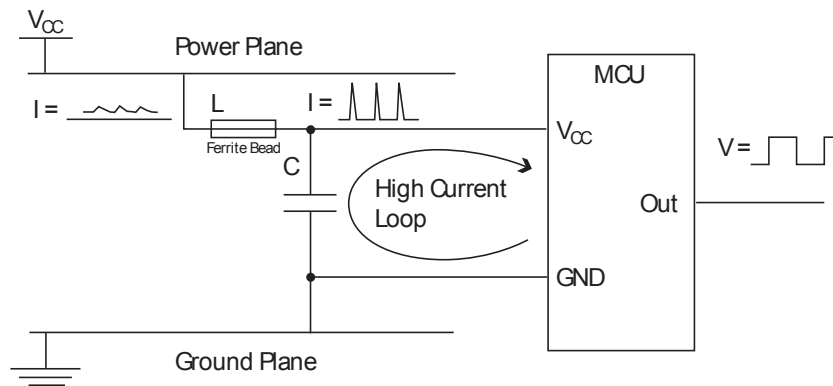
Figure 2-1. Incorrect Decoupling



The figure above shows an example of insufficient decoupling. The capacitor is placed too far away from the microcontroller, creating a larger high-current loop. The power and ground planes are part of the high-current loop. As a result, noise is spread more easily to other devices on the board and radiated emission from the board is increased even further. The whole ground plane will act as an antenna for the noise, instead of only the high-current loop. This will be the case when the power and ground pins are connected directly to the planes (typical for hole-mounted components) and the decoupling capacitor is connected to the planes some distance away. This is sometimes observed in boards with surface-mount components where the integrated circuits are placed on one side of the board and the decoupling capacitors are placed on the other side.

The figure below shows a better placement of the capacitor. The lines that are part of the high-current loop are not part of the power or ground planes. This is important, as the power and ground planes otherwise will spread a lot of noise. The figure also shows another method of improving decoupling; a series ferrite bead is inserted to reduce the switching noise on the power plane. The series impedance of the ferrite bead should be low enough to ensure that there is no significant drop in the DC voltage. The ferrite bead may not be necessary, especially if the power supply itself is sufficiently filtered.

Figure 2-2. Decoupling with Series Inductor



Another decoupling alternative is to connect the device power and ground pins directly to the planes and connect the decoupling capacitor(s) to the planes *as close as possible* to the power and ground pins. For large packages, placing decoupling capacitors on the opposite side of the board may be the best way of getting them as close as possible to the power and ground pins. Also, in this approach, it is critical to minimize the loop area formed between the decoupling capacitor and device power and ground pin. The downside of this approach is that power plane noise can more easily be coupled to the device power supply - thus making sure that the power plane is properly filtered in general becomes more important.

In AVR devices, where power and ground pins are placed close together, there will be better decoupling than in devices with industry standard pinout. In industry standard pinout, the power and ground pins are placed in opposite corners of the DIP package. For devices with multiple pairs of power and ground pins, it is essential that there is a decoupling capacitor for every pair of pins.

The main power supply should also have a tantalum or ceramic capacitor to stabilize it.

2.2 Analog Supply

AVR devices that have a built-in ADC may have a separate analog supply voltage pin, $A_{V_{CC}}$. This separate voltage supply ensures that the analog circuits are less prone to the digital noise that originates from the switching of the digital circuits.

To improve the accuracy of the ADC, the analog supply voltage must be decoupled separately, similar to the digital supply voltage. AREF must also be decoupled. The typical value of the capacitor is 100 nF. If a separate analog ground (AGND) is present, the analog ground should be separated from the digital ground so that the analog and digital grounds are connected only at a single point (at the power supply GND).

3. Connection of RESET Pin on AVR Devices

The RESET pin on the AVR device is active-low, and setting the pin low externally will reset the device.

The Reset has two purposes:

1. To release all the lines by tri-stating all pins (except XTAL pins), initialize all I/O registers and set the Program Counter (PC) to zero.
2. To enter Programming mode (for some parts, the PEN line is also used to enter Programming mode). It is also possible to enter High-Voltage/Parallel Programming (HVPP) mode by drawing the RESET pin very high (11.5V – 12.5V). Refer to the respective device data sheet for more specific information about the RESET pin and its functionality.

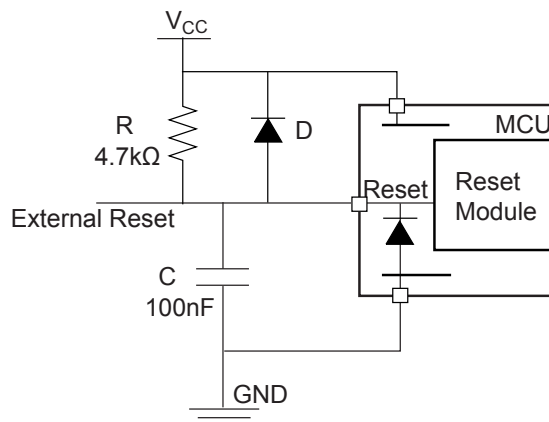
The Reset line has an internal pull-up resistor. If the environment is noisy, it can be insufficient and Reset may occur sporadically. Refer to the device data sheet for the value of the pull-up resistor that must be used for specific devices.

Connecting the Reset so that it is possible to enter both high-voltage programming and ordinary low-level Reset can be achieved by using a pull-up resistor to the Reset line. This pull-up resistor avoids any unintended low signal that will trigger a Reset. Theoretically, the pull-up resistor can be of any value, but if the AVR device should be programmed using an external programmer, the pull-up should not be in such a high state that the programmer is not able to activate Reset by drawing the Reset line low. The recommended pull-up resistor value is 4.7 k Ω or larger when using STK[®]600 for programming. For DebugWIRE to function properly, the pull-up must not be less than 10 k Ω .

To protect the Reset line from further noise, connect a capacitor from the RESET pin to ground. This is not directly required since AVR devices internally have a low-pass filter to eliminate spikes and noise that could cause reset. Using an extra capacitor is an additional protection. However, such extra capacitor cannot be used when DebugWIRE or PDI is used.

ESD protection diode is not provided internally from Reset to V_{CC} in order to allow HVPP. If HVPP is not used, it is recommended to add an ESD protection diode externally from Reset to V_{CC} . Alternatively, a Zener diode can be used to limit the Reset voltage relative to GND. A Zener diode is highly recommended in noisy environments. The components should be located physically close to the RESET pin of the AVR device. A recommended circuit of a Reset line is shown in the following circuit diagram.

Figure 3-1. Recommended Reset Pin Connection



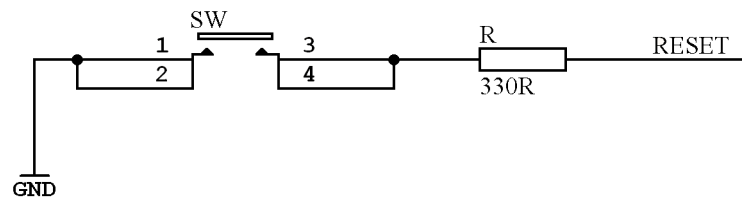
Note: The values of resistor R and capacitor C are typical values used for the RESET pin. For specific design requirements of an application, these values must be changed accordingly.

3.1 External RESET Switch

If an external switch is connected to the RESET pin, it is important to add a series resistance. Whenever the switch is pressed it will short the capacitor, and the current (**I**) through the switch can have high peak values. This causes the switch to bounce and generate steep spikes in 2 ms - 10 ms (**t**) periods until the capacitor is discharged. The PCB tracks and the switch metal introduces a small inductance (**L**) and the high current through these tracks can generate high voltages up to $V_L = L * di/dt$.

This spike voltage, V_L , is most likely outside the specification of the RESET pin. By adding a series resistor between the switch and the capacitor, the peak currents generated will be significantly low and it will not be large enough to generate high voltages at the RESET pin. An example connection is shown in the following diagram.

Figure 3-2. Switch Connection for Reset Pin



4. Connecting Programmer/Debugger Lines

AVR microcontrollers feature one or more interfaces for programming or debugging. In-System Programming (ISP) is a programming interface used for programming the Flash, EEPROM, Lock bits, and Fuse bits in almost all AVR devices. This feature makes it possible to program the AVR microcontroller in the last stage of production of a target application board, reprogram if SW bugs are identified late in the process, or update the AVR device in the field, if required. Some ISP interfaces may also be used for on-chip debugging. It is therefore recommended to design the target application board so that the ISP connectors are easily accessible.

Note: Refer to the device-specific data sheet for information on the programming/debugging interfaces supported by the device.

4.1 SPI Programming Interface

On devices that use a Serial Peripheral Interface (SPI) for ISP, these lines are usually located on the same pins as a regular SPI, or on pins that can be used for other purposes. Refer to the device data sheet to determine the pins used for the ISP.

Two standard SPI connectors are provided by the ISP programmers; a 6-pin and a 10-pin connector. In addition to the data lines (MOSI and MISO) and the bus clock (SCK), the target voltage VTG, GND, and Reset (RST) are also provided through these connectors.

Figure 4-1. Connections for the 6- and 10-pin ISP Headers



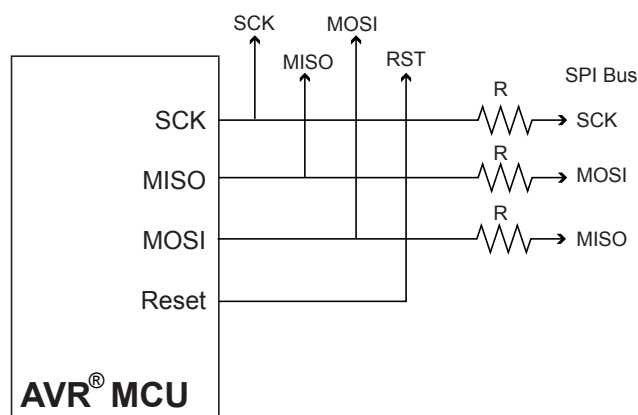
A few ISP programmers are powered by the target power supply. In this way they easily adapt to the correct voltage level of the target board. Other ISP programmers, such as STK600, can alternatively power the target board via the VTG line. In such a case, it is important that the power supply on the target is not switched on.

Note: Refer to the respective programmer user guide for more information on the capabilities and physical interface.

4.1.1 Shared Use of SPI Programming Lines

If additional devices are connected to the ISP lines, the programmer must be protected from any device, other than the AVR device, that may try to drive the lines. This is important with the SPI bus, as it is similar to the ISP interface. Applying series resistors on the SPI lines, as depicted in [Connecting the SPI Lines to the ISP Interface](#), is the easiest way to achieve this. Typically, the resistor value R can be of 330Ω⁽¹⁾.

Figure 4-2. Connecting the SPI Lines to the ISP Interface

**Note:**

1. These typical values are used to limit the input current to 10 mA for a supply voltage (V_{CC}) of 3.3V. It may vary depending on the programmer/debugger used and the requirements of specific hardware design.
2. The AVR device will never drive the SPI lines in a programming situation. The AVR device is held in Reset to enter Programming mode, which puts all AVR device pins to tri-states.

In a single application, multiple AVR devices can share the same ISP interface. This enables programming of all the devices through a minimal interface. However, if there are no special design considerations, then all the AVR devices will respond to the ISP instructions. The SPI clock lines should be separately provided (can be gated using jumpers or DIP switches) so that only one AVR device at a time receives SPI clock. Other SPI lines (MOSI and MISO) can be shared. This method ensures that AVR devices are separated from the programmer by the same protection resistors since they are all held in Reset while the ISP Reset line is activated. The ISP clock can be gated using jumpers or DIP switches.

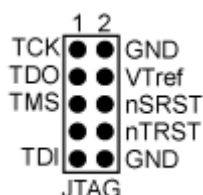
An alternate solution is to use multiple ISP interfaces, one for each device, all protected separately with series resistors.

4.2 JTAG Interface

Few devices have a JTAG interface that can be used for both programming and debugging. The JTAG lines are shared with analog input and must be connected so that the JTAG programmer can control the lines. JTAG programming tools can drive a resistive load, however, it is better to avoid capacitive load.

The following figure shows the standard JTAG connector supplied with ISP programmers. For the SPI programming connector, the target's voltage supply allows power to the device or ensures correct signal levels when programming.

Figure 4-3. Pinout of the Standard JTAG Connector

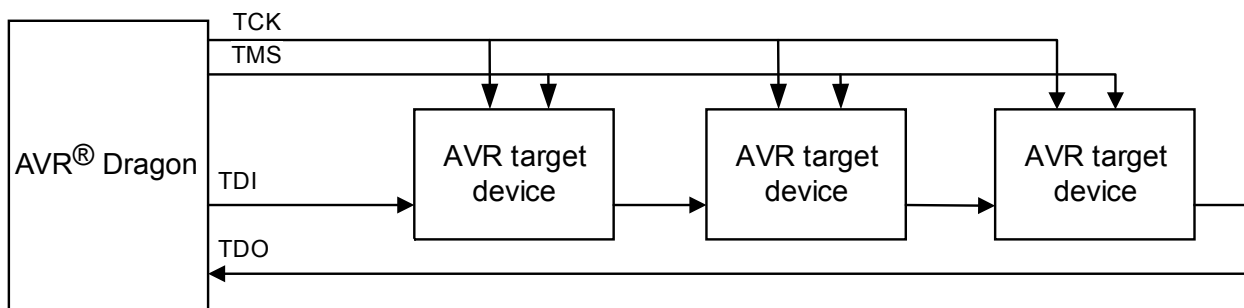


Note: Refer to the specific user guide of programmers/debuggers for more information about the JTAG interfacing with AVR devices.

4.2.1 Shared Use of JTAG Lines

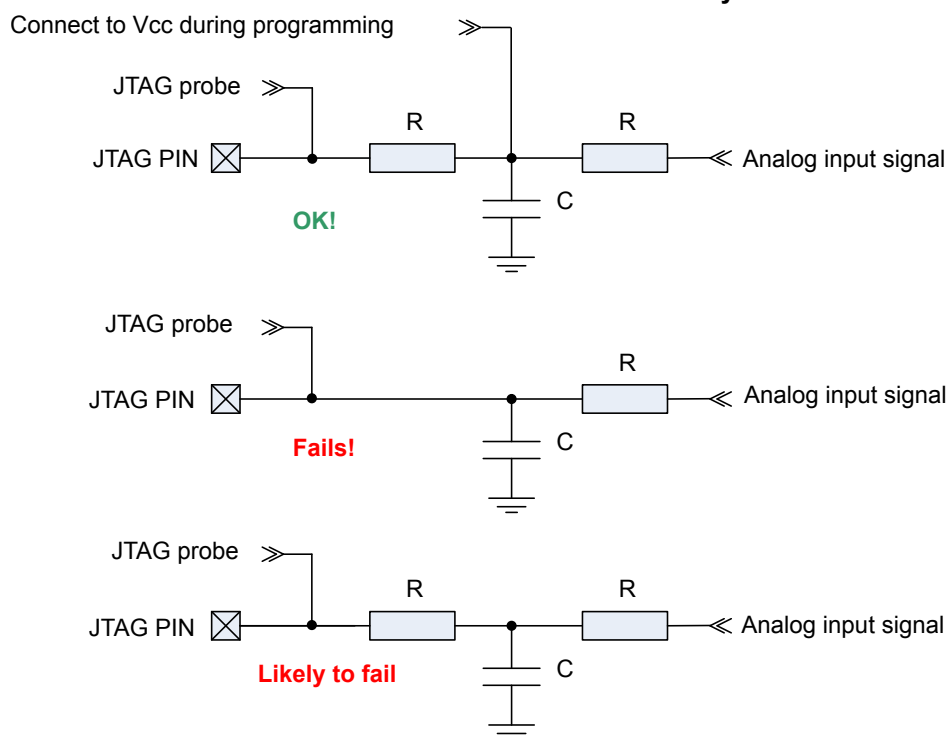
By creating a JTAG daisy-chain, a single JTAG connector can serve as an ISP interface for several devices. Typical connection for a daisy-chain using JTAG for AVR[®] Dragon is shown in the following schematic. The daisy-chain configuration can be used for any programmer/debugger that uses JTAG interface. The GND and VT_{REF} of JTAG, which is not shown in the figure, must be connected to the target board.

Figure 4-4. JTAG Daisy-Chain



The protection resistors shown in Figure 4-2 are required if the JTAG lines are used in the application. For example, ADC input pins often have analog filters on the lines. In such cases, the filter capacitor must be removed while programming, to ensure that the load is resistive. The following figure illustrates the steps.

Figure 4-5. JTAG Interface Connections – Correct and Incorrect Ways

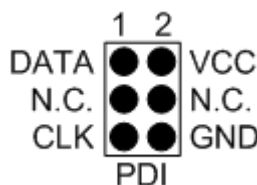


4.3 PDI Interface

The Program and Debug Interface (PDI) is a Microchip proprietary two-line interface that was introduced with the AVR XMEGA[®] microcontroller family. As the name implies, this interface can be used for both In-System Programming and on-chip debugging of devices.

The following figure shows the standard PDI connector supplied with Microchip programmers. Only two pins on the device are required for using this interface; RESET, also called PDI_CLK, and the dedicated PDI_DATA pin. The target's voltage supply allows power to the device or ensures correct signal levels during programming.

Figure 4-6. Standard PDI Header



Note: Refer to the respective programmer user guide for more information about the capabilities and physical interface of PDI.

4.3.1 External Reset Circuitry

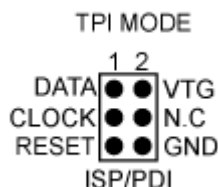
Since the Reset line is used for clocking the PDI, it is important to bypass or avoid any circuitry that can distort the clock signal during programming or debugging, such as capacitors and external reset sources. During normal operation, the RESET pin has an internal filter to prevent unintentional resets such as those caused by short spikes on the Reset line. Despite the fact that the clock signal is deformed, capacitive loads up to 1 nF have been tested to work with the STK600 and AVR Dragon during programming. Pull-up resistors should be at least 10 kΩ or removed from the Reset line if a Microchip programmer is used.

4.4 TPI Interface

The Tiny Programming Interface is featured on the tinyAVR® devices with the lowest pin count.

The following figure shows the standard TPI connector supplied along with the Microchip programmer device. Only three pins on the device are required for use of this interface; RESET, TPICLK, and TPIDATA. The latter two pins are multiplexed with regular I/O pins.

Figure 4-7. Standard TPI Header



The RESET pin can be reconfigured as an I/O pin by programming the RSTDISBL fuse of the device. This disables the reset functionality and requires +12V to be applied to Reset for programming to work. Only a few programming tools are capable of generating this voltage.

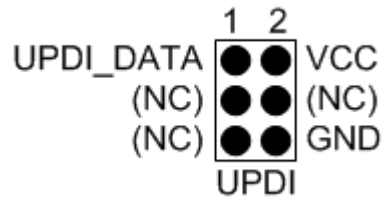
Note: Refer to the respective programmer user guide for more information about the capabilities and physical interface of TPI.

4.5 UPDI Interface

The Unified Program and Debug Interface (UPDI) is a Microchip proprietary interface for external programming and on-chip debugging of a device.

Programming and debugging are performed using the UPDI Physical interface (UPDI PHY), which is a UART-based half-duplex 1-wire interface for data reception and transmission. It uses the Reset line to detect the debugger probe.

Figure 4-8. Standard UPDI Header



Single-wire interface can be enabled by setting a fuse or by 12V programming, which disables the reset functionality. Not all programming tools are capable of generating this voltage.

Note: Refer to the respective programmer user guide for more information about the capabilities and physical interface of UPDI.

5. Using Crystal and Ceramic Resonators

Most AVR MCUs can use different clock sources. The optional external clock sources are external clock, RC oscillator, crystal, or ceramic resonator. The use of crystals and ceramic resonators cause problems in some designs due to the fact that the use of these clock sources is not well understood. This section addresses the topic of using crystals and ceramic resonators in relation to the AVR MCUs. The description focuses on features and parameters relevant for designing applications where crystals or ceramic resonators are used rather than trying to be a complete description of the theory related to the topic. For more information and theory regarding crystals, refer to application note [“AVR4100: Selecting and Testing 32kHz Crystal Oscillators for AVR Microcontrollers”](#).

5.1 Selecting the Clock Source in the AVR MCU

The clock source used by the AVR devices are selected by setting the appropriate fuses. However, for the AVR XMEGA family, the clock source is configured using software. Most ISP and parallel programmers can program the fuses for selecting a clock source. The fuses are not erased when the AVR device memory is erased and the fuses must only be programmed if the fuse settings should be altered. Programming the fuses each time the device is erased and reprogrammed is thus not necessary. The clock options that are relevant for this document are:

- External low-frequency crystal
- External crystal oscillator
- External ceramic resonator

Several sub-settings related to the start-up time of the AVR device can be selected, but the three clock options mentioned are the fundamental settings that should be focused on. The clock options can vary across different AVR devices, as not all devices support external oscillators. Refer to the device-specific data sheet to determine the available clock options.

The AVR device may not run if a different clock source other than the clock source actually configured is selected. The oscillator circuits are activated internally in the AVR device, based on the configured clock option. The fuses are not cleared by a memory erase. Hence, it can cause problems if incorrect settings are selected.

5.2 About Crystals and Ceramic Resonators

The typical crystal used for the AVR device is the AT-cut parallel resonant crystal. The ceramic resonator is very similar to the AT-cut parallel resonant crystal but is a low-cost, low-quality version of the crystal. The ceramic resonator has a lower Q-value, which is both an advantage and disadvantage. Due to the lower Q-value, the oscillator frequency of the ceramic resonator can more easily be tuned to the desired frequency. But, it is also more sensitive to temperature and load changes, causing undesired frequency variations. The advantage of the ceramic resonator is that it has a faster start-up than crystals.

In this section, the term *resonator* refers to both Quartz Crystals and Ceramic Resonator.

	Ceramic Resonator	Quartz Crystal
Aging	±3000 ppm	±10 ppm
Frequency tolerance	±5000 ppm*	±20 ppm
Frequency temperature characteristics	±50 ppm/°C*	±0.5 ppm/°C

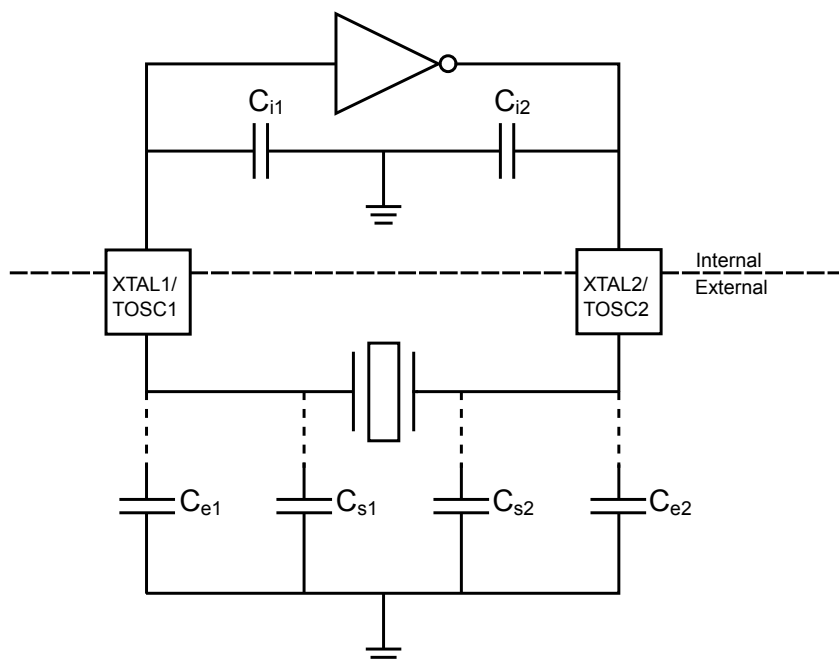
	Ceramic Resonator	Quartz Crystal
Frequency pull-ability	± 350 ppm/pF*	± 15 ppm/pF
Oscillator rise time	0.01 ms - 0.5 ms	1 ms - 10 ms
Quality factor (Qm)	100 - 5000	$10^3 - 5 \times 10^5$

Note: The information provided in the table is to showcase the differences. For more details about the oscillator, refer to the device-specific data sheet.

Note: * The ppm variation in the ceramic resonator depends on the quality of the ceramic resonator.

The parallel resonator is used in circuits which contain reactive components such as capacitors. Such circuits depend on the combination of the reactive components and the resonator to accomplish the phase shift required to start and maintain the oscillation at a specific frequency. Basic oscillator circuits used for parallel resonators are illustrated in the following diagram. The part of the circuit above the dashed line represents the oscillator circuit present internally in the AVR device. Simply, the AVR device built-in oscillator circuits can be understood as an inverter-based oscillator circuit, as shown in the following figure.

Figure 5-1. Basic Inverter Circuits Equivalent to the Oscillator Circuits in AVR Devices



The circuit depicted in [Figure 5-1](#) includes internal capacitive load (C_i), the stray capacitance (C_s) of a circuit, and the optional external capacitance (C_e) to match the capacitive load (C_L) of the resonator.

Note: Some AVR devices may not include internal capacitors, or may have a fuse setting to enable/disable the internal capacitors. Always check the device data sheet before choosing the resonator.

When using resonators with the AVR device, it may be necessary to apply (external) capacitors according to the requirements of the resonator used. A parallel resonator will not be able to provide stable oscillation if an insufficient capacitive load is applied. When the capacitive load is too high, the oscillation may not start as expected due to drive level dependency of the load. The capacitive load of the crystal (C_L), found in the data sheet of the resonator, is the recommended capacitive load of the resonator (viewed from the terminals of the resonator). To match the capacitive load (C_L) the engineer must

calculate the external capacitors (C_e) using Equation - 1. The closer the total capacitance of C_i , C_s , and C_e are to C_L , the more exact the frequency one should get.

Equation - 1

$$\Sigma C_L = \frac{(C_{i1} + C_{e1} + C_{s1})(C_{i2} + C_{e2} + C_{s2})}{C_{i1} + C_{i2} + C_{e1} + C_{e2} + C_{s1} + C_{s2}}$$

Where C_{e1} and C_{e2} refer to the external capacitors seen in the figure above, and C_{s1} and C_{s2} are stray capacitances at the XTAL/TOSC pins of the AVR device, and C_{i1} and C_{i2} are the internal capacitances.

Assuming symmetric layout, so that C_{i1} and $C_{i2} = C_i$ and C_{s1} and $C_{s2} = C_s$ (C_s can be estimated to be 2 pF - 5 pF), and then the external capacitors can be determined by the following equation, with C_L given by resonator data sheet.

Equation - 2

$$C_e + C_i = 2C_L - C_s$$

- C_e - is optional external capacitors as shown in [Figure 5-1](#).
- C_i - is the pin capacitance of the XTAL and/or TOSC pin of the desired device.
- C_L - is the load capacitance of the desired crystal.
- C_s - is the total stray capacitance for one pin.

Examples are given in chapter [Example Layout of ATxmega32A4 and ATmega324PB Devices](#).

5.3 Recommended Capacitor Values



Important:

Recommendations given in this chapter are guiding values only. Always check the data sheet, and calculate values accordingly.

When using the external crystal oscillator on non-PB AVR devices, crystals with a nominal frequency range starting from 400 kHz can be used. For the standard high-frequency crystals, the recommended capacitor value range is in the range of 22 pF - 33 pF. For the newer AVR PB, the recommended capacitor value range is 12 pF - 22 pF, the total capacitance ($C_e + C_i + C_s$) for each pin must not exceed 22 pF.

The external low-frequency crystal is intended for 32.768 kHz crystals. When selecting this clock source, the internal oscillator circuit might provide the required capacitive load. By programming the CKOPT Fuse ⁽¹⁾, the user can enable internal capacitors on XTAL1 and XTAL2. The value of the internal capacitor is typical 20 pF but can vary. External capacitors are not required when using a 32.768 kHz crystal that does not require more load. Then the value of the external capacitor can be determined using the *Equation - 2*. The CKOPT Fuse should not be programmed when using external capacitors.

In other cases, an external capacitive load specified by the manufacturer of the crystal must be used.

When using the external ceramic resonator, refer to the device data sheet for determining the capacitors values. Always use the recommended capacitive load, as the resonant frequency of the ceramic resonator is very sensitive to capacitive load.

Note:

1. Some AVR devices may not come with internal capacitors. Some AVR devices may not have the CKOPT fuse, instead they have dedicated pins (TOSC1-TOSC2), to connect the 32.768 kHz crystal.
2. Refer to the device data sheet for specific details related to oscillator connections.

5.4 Unbalanced External Capacitors

In noisy environments the oscillator can be crucially affected. If the noise is strong enough, the oscillator can “lock up” and stop oscillating. To reduce the sensitivity of the oscillator to noise, the size of the capacitor at the high-impedance input of the oscillator circuit, XTAL1, can be slightly increased. Increasing only one of the capacitors does not affect the total capacitive load much, but unbalanced capacitors can affect the resonant frequency to a higher degree than the change of the total capacitive load. However, unbalanced capacitive loads will affect the duty cycle of the oscillation and should not be used. This is especially critical if the AVR device is utilized close to its maximum speed limit.

5.5 RTC Crystals

Many AVR devices have the capability of using asynchronous clocking of the built-in timer/counter. Using this feature, the counter can be used for real-time functions. A 32.768 kHz crystal should be connected to the TOSCx pins of the AVR device.

In some AVR devices, the internal oscillator circuit used with the real-time counter provides a capacitive load of approximately 20 pF, which should be appropriate for common 32.768 kHz crystals. Refer to the device-specific data sheet for information about the capacitors. If the internal load is insufficient for the applied crystal, external capacitors can be used.

5.6 PCB Layout

Finally, the physical location of the resonator, with respect to the AVR device, is important. Ensure that the resonator is placed as close as possible to the AVR device and shield the resonator by surrounding it with a ground plane.

6. Unused XTAL Pins

If XTAL pins are not in use, they should be tied to ground. This helps to prevent unintentional behavior during device start-up.

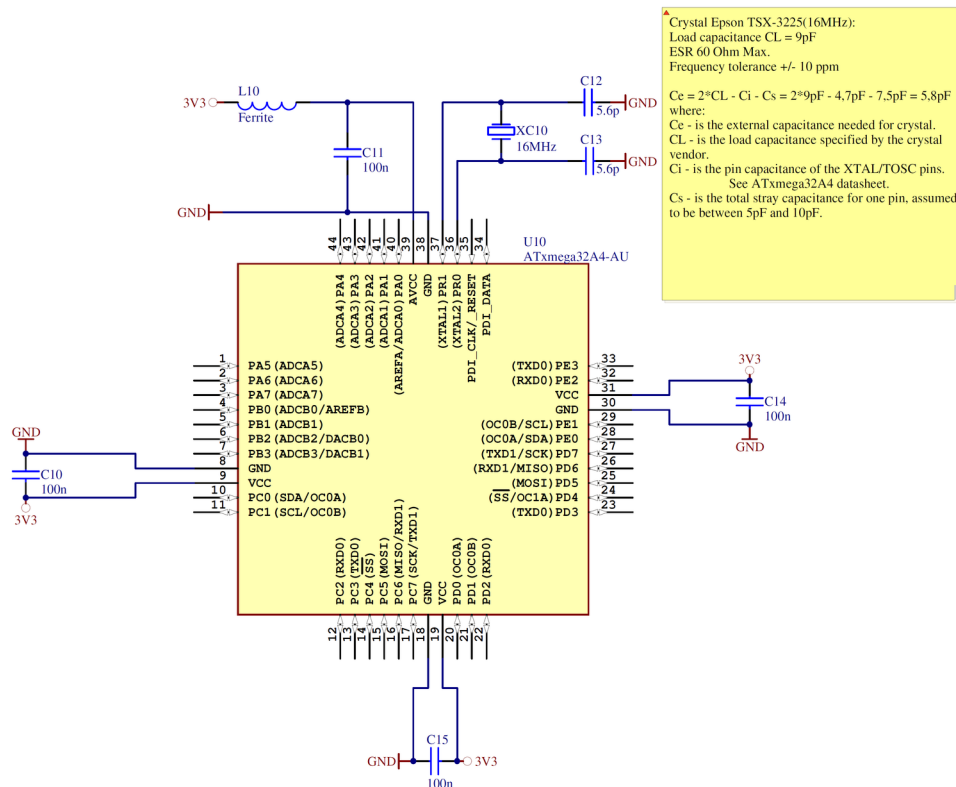
7. Example Layout of ATxmega32A4 and ATmega324PB Devices

The following schematic- and layout examples are recommended starting points for ATxmega32A and ATmega324PB designs. Always check the respective data sheets to ensure the correct values are used for all components. The key points to be considered are:

1. The connections for crystal oscillator and decoupling capacitors.
2. The number of layers on the PCB. It is recommended to have a multilayer design with supply and ground plane on separate layers.
3. Decoupling of all digital supply pairs from V_{CC} and isolating AV_{CC} from V_{CC} .
4. Short distance between the crystal/capacitors and the MCU.
5. Ground plane surrounding the crystal and the vias connected to the planes are close to the MCU pins in the layout.

Note: For ATmega PB devices, the total amount of capacitance must not exceed 22 pF. This includes PCN traces and pin capacitance.

Figure 7-1. ATxmega32A4 - Basic Schematic Example of Required/Recommended Connections



Example Layout of ATxmega32A4 and ATmega324PB ...

Figure 7-2. ATxmega32A4 - Copper PCB Layout of Required/Recommended Connections

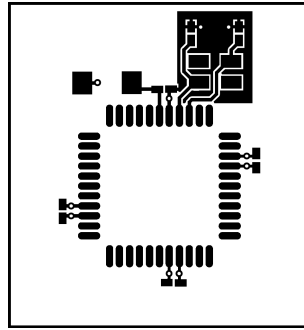


Figure 7-3. ATxmega32A4 - Top Silk Prints of Required/Recommended Connections

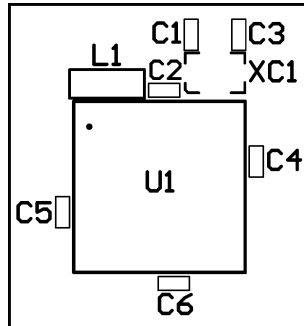


Figure 7-4. ATmega324PB - Basic Schematic Example of Required/Recommended Connections

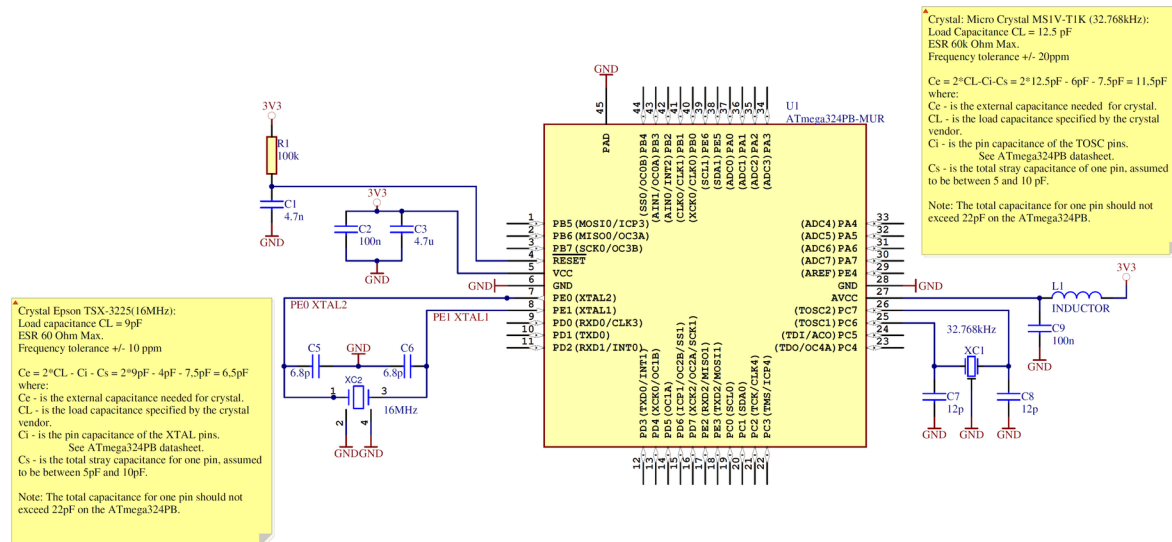


Figure 7-5. ATmega324PB - Copper PCB Layout of Required/Recommended Connections

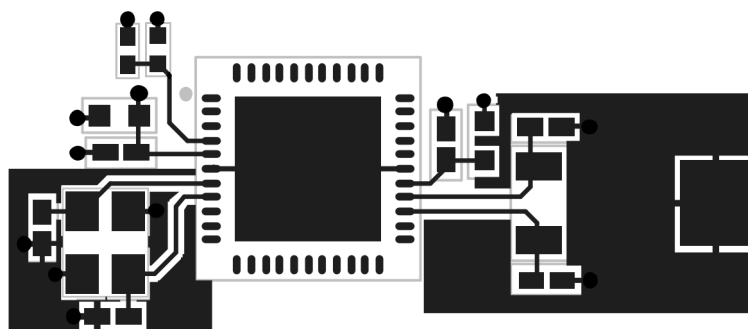
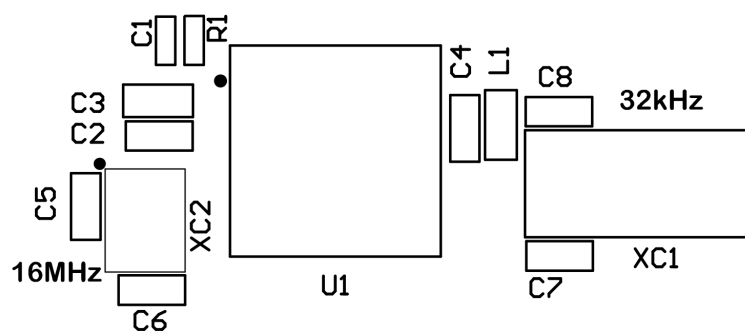


Figure 7-6. ATmega324PB - Top Silk Prints of Required/Recommended Connections



8. Revision History

Doc Rev.	Date	Comments
B	02/2018	<ol style="list-style-type: none"> 1. Explanations in the Digital Supply section were improved. 2. Obsolete section on Noise Implications was removed.
A	08/2017	<ol style="list-style-type: none"> 1. Chapter “Unused XTAL Pins” is added. 2. A note for the Example Layout has been added. 3. New document template. Microchip DS00002519A replaces Atmel 2521S.
2521R	09/2016	<ol style="list-style-type: none"> 1. The filename and the document number in part of this revision history have been corrected. 2. Trademark corrections. 3. Some minor corrections in the text.
2521Q	06/2016	<ol style="list-style-type: none"> 1. General improvement of descriptions. 2. Added example layout for ATmega324PB device.
2521P	10/2015	Updated the following sections: <ol style="list-style-type: none"> 1. About Crystals and Ceramic Resonators 2. Recommended Capacitor Values
2521O	09/2015	Corrected the figure Example Layout .
2521N	06/2015	Added Noise Implications.
2521M	09/2014	Fixed some typos in External RESET Switch .
2521L	07/2013	<ol style="list-style-type: none"> 1. Updated Figure 4-5. 2. General improvements in regards of descriptions.

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